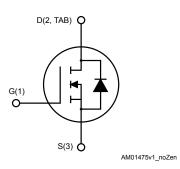




# N-channel 100 V, 33 mΩ typ., 25 A, STripFET™ II Power MOSFET in a DPAK package

# TAB O 2 3

DPAK



#### **Features**

Туре	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STD25NF10T4	100 V	38 mΩ	25 A

- Exceptional dv/dt capability
- 100% avalanche tested
- · Low gate charge

#### **Applications**

· Switching applications

#### **Description**

This Power MOSFET series has been developed using STMicroelectronics' unique STripFET™ process, which is specifically designed to minimize input capacitance and gate charge. This renders the device suitable for use as primary switch in advanced high-efficiency isolated DC-DC converters for telecom and computer applications, and applications with low gate charge driving requirements.

Product status link
STD25NF10T4

Product summary			
Order code STD25NF10T4			
Marking D25NF10			
Package	DPAK		
Packing	Tape and reel		



# 1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	100	V
$V_{DGR}$	Gate-source voltage (R <sub>GS</sub> = 20 k $\Omega$ )	100	V
V <sub>GS</sub>	Gate-source voltage	±20	V
1-	Drain current (continuous) at T <sub>C</sub> = 25 °C	25	Α
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	21	Α
I <sub>DM</sub> <sup>(1)</sup>	Drain current (pulsed)	100	Α
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	100	W
E <sub>AS</sub> <sup>(2)</sup>	Single-pulse avalanche energy	480	mJ
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	13	V/ns
T <sub>stg</sub>	Storage temperature range	-55 to 175	°C
T <sub>j</sub>	Operating junction temperature range	-55 to 175	

- 1. Pulse width limited by safe operating area.
- 2. Starting  $T_J$  = 25 °C,  $I_D$  = 12.5 A,  $V_{DD}$  = 50 V
- 3.  $I_{SD} \le 25~A,~di/dt \le 300~A/\mu s,~V_{DS} \le V_{(BR)DSS},~T_J \le T_{JMAX}$

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case	1.5	°C/W
R <sub>thj-pcb</sub> <sup>(1)</sup>	Thermal resistance junction-pcb	50	°C/W

1. When mounted on an FR-4 board of 1 inch<sup>2</sup>, 2 oz Cu.

DS2063 - Rev 5 page 2/18



### 2 Electrical characteristics

 $T_{CASE}$  = 25 °C unless otherwise specified

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
		V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 100 V			1	μA
I <sub>DSS</sub>	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V},$ $T_{C} = 125 ^{\circ}\text{C}^{(1)}$			10	μA
I <sub>GSS</sub>	Gate body leakage current	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V			±100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DD} = V_{GS}, I_{D} = 250 \mu A$	2	3	4	V
R <sub>DS(on)</sub>	Static drain-source on-resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12.5 A		33	38	mΩ

<sup>1.</sup> Defined by design, not subject to production test.

**Table 4. Dynamic** 

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>DS</sub> = 25 V, f = 1 MHz,	-	1550	-	pF
C <sub>oss</sub>	Output capacitance	V <sub>DS</sub> = 23 V, 1 = 1 Wil 12,	-	220	-	pF
C <sub>rss</sub>	Reverse transfer capacitance	VGS 0 V	-	95	-	pF
Qg	Total gate charge	V <sub>DD</sub> = 80 V, I <sub>D</sub> = 25 A,	-	55	-	nC
Q <sub>gs</sub>	Gate-source charge	V <sub>GS</sub> = 0 to 10 V	-	12	-	nC
$Q_{gd}$	Gate-drain charge	(see Figure 12. Test circuit for gate charge behavior)	-	20	-	nC

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> = 50 V, I <sub>D</sub> = 12.5 A,	-	17	-	ns
t <sub>r</sub>	Rise time	$R_G = 4.7 \Omega$ , $V_{GS} = 10 V$	-	60	-	ns
t <sub>d(off)</sub>	Turn-off delay time	(see Figure 11. Test circuit for resistive load switching times and	-	60	-	ns
t <sub>f</sub>	Fall time	Figure 16. Switching time waveform)	-	15	-	ns

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub>	Source-drain current		-		25	Α
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current (pulsed)		-		100	Α
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	I <sub>SD</sub> = 25 A, V <sub>GS</sub> = 0 V	-		1.5	V

DS2063 - Rev 5 page 3/18



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>rr</sub>	Reverse recovery time	$I_{SD} = 25 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s,}$	-	88		ns
Q <sub>rr</sub>	Reverse recovery charge	V <sub>DD</sub> = 50 V, T <sub>J</sub> = 150 °C	-	317		nC
I <sub>RRM</sub>	Reverse recovery current	(see Figure 16. Switching time waveform)	-	7.2		Α

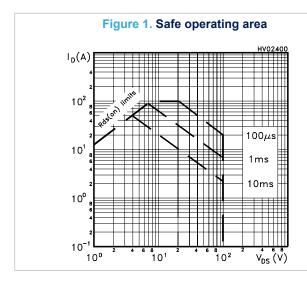
<sup>1.</sup> Pulse width limited by safe operating area

DS2063 - Rev 5 page 4/18

<sup>2.</sup> Pulsed: pulse duration = 300  $\mu$ s, duty cycle 1.5%



#### 2.1 Electrical characteristics (curves)



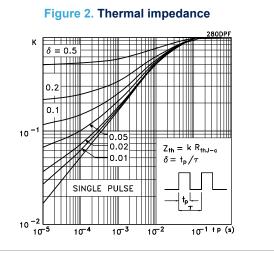


Figure 3. Output characteristics

HV02065

Vcs=10V

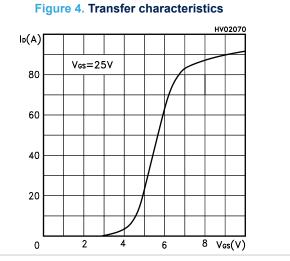
80

60

40

20

5 10 15 20 Vcs(V)



DS2063 - Rev 5 page 5/18



Figure 5. Gate charge vs gate-source voltage

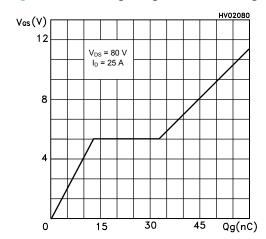


Figure 6. Static drain-source on-resistance

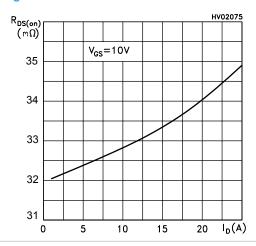


Figure 7. Source-drain diode forward characteristics

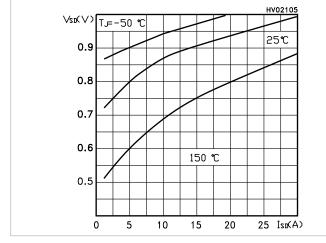


Figure 8. Capacitance variations

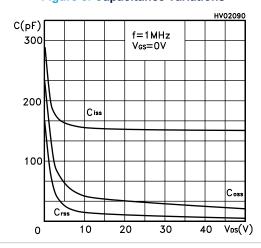


Figure 9. Normalized gate threshold voltage vs temperature

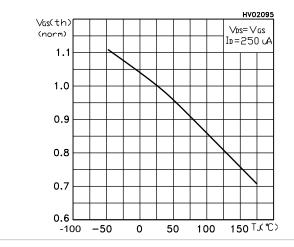
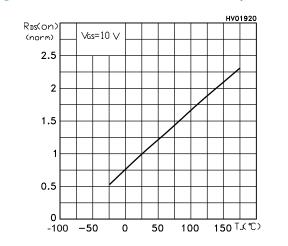


Figure 10. Normalized on-resistance vs temperature



DS2063 - Rev 5 page 6/18



#### 3 Test circuits

Figure 11. Test circuit for resistive load switching times

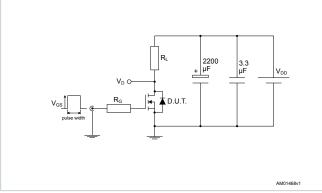


Figure 12. Test circuit for gate charge behavior

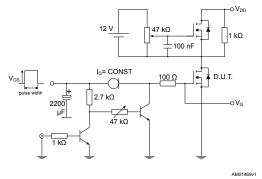


Figure 13. Test circuit for inductive load switching and diode recovery times

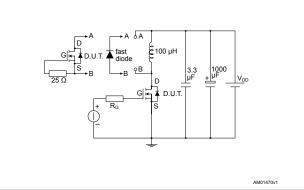


Figure 14. Unclamped inductive load test circuit

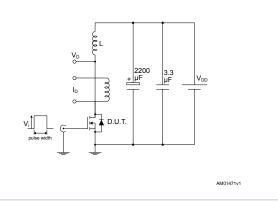


Figure 15. Unclamped inductive waveform

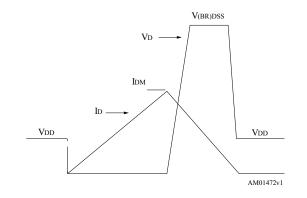
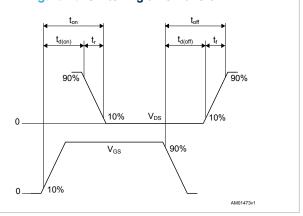


Figure 16. Switching time waveform



DS2063 - Rev 5 page 7/18



# 4 Package information

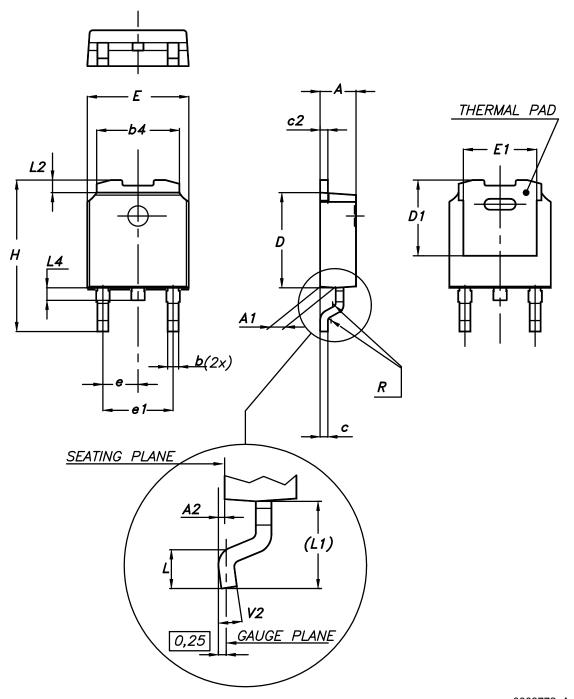
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

DS2063 - Rev 5 page 8/18



### 4.1 DPAK (TO-252) type A package information

Figure 17. DPAK (TO-252) type A package outline



0068772\_A\_25

DS2063 - Rev 5 page 9/18



Table 7. DPAK (TO-252) type A mechanical data

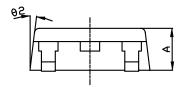
Dim.		mm	
Dilli.	Min.	Тур.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
С	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
е	2.159	2.286	2.413
e1	4.445	4.572	4.699
Н	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

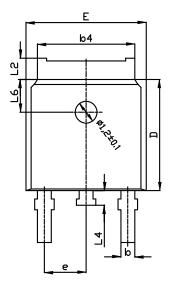
DS2063 - Rev 5 page 10/18

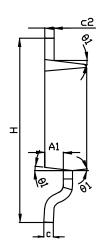


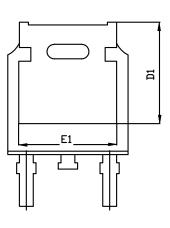
# 4.2 DPAK (TO-252) type C2 package information

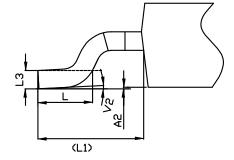
Figure 18. DPAK (TO-252) type C2 package outline











0068772\_C2\_25

DS2063 - Rev 5 page 11/18



Table 8. DPAK (TO-252) type C2 mechanical data

Dim.	mm			
Dilli.	Min.	Тур.	Max.	
Α	2.20	2.30	2.38	
A1	0.90	1.01	1.10	
A2	0.00		0.10	
b	0.72		0.85	
b4	5.13	5.33	5.46	
С	0.47		0.60	
c2	0.47		0.60	
D	6.00	6.10	6.20	
D1	5.10		5.60	
E	6.50	6.60	6.70	
E1	5.20		5.50	
е	2.186	2.286	2.386	
Н	9.80	10.10	10.40	
L	1.40	1.50	1.70	
L1		2.90 REF		
L2	0.90		1.25	
L3		0.51 BSC		
L4	0.60	0.80	1.00	
L6		1.80 BSC		
θ1	5°	7°	9°	
θ2	5°	7°	9°	
V2	0°		8°	

DS2063 - Rev 5 page 12/18



Figure 19. DPAK (TO-252) recommended footprint (dimensions are in mm)

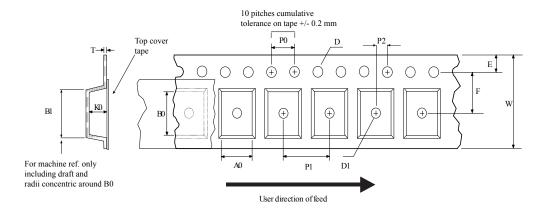
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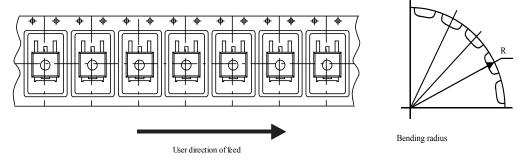
DS2063 - Rev 5 page 13/18



### 4.3 DPAK (TO-252) packing information

Figure 20. DPAK (TO-252) tape outline



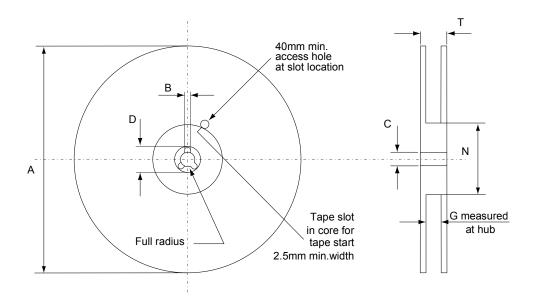


AM08852v1

DS2063 - Rev 5 page 14/18



Figure 21. DPAK (TO-252) reel outline



AM06038v1

Table 9. DPAK (TO-252) tape and reel mechanical data

Таре			Reel		
Dim.	mm		Dim.	mm	
Dim.	Min.	Max.	Jim.	Min.	Max.
A0	6.8	7	А		330
В0	10.4	10.6	В	1.5	
B1		12.1	С	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	Т		22.4
K0	2.55	2.75			
P0	3.9	4.1	Bas	se qty.	2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
Т	0.25	0.35			
W	15.7	16.3			

DS2063 - Rev 5 page 15/18



### **Revision history**

Table 10. Document revision history

Date	Version	Changes
21-Jun-2004	3	Preliminary version
03-Jul-2006	4	New template, no content change
		Updated information on cover page.
09-Aug-2018	5	Updated Section 4 Package information.
		Minor text changes

DS2063 - Rev 5 page 16/18



### **Contents**

1	Elec	trical ratingstrical ratings	2		
2	Electrical characteristics				
	2.1				
3	Test	circuits			
4	Pac	Package information			
	4.1	DPAK (TO-252) type A package information	8		
	4.2	DPAK (TO-252) type C2 package information	10		
	4.3	DPAK (TO-252) packing information	13		
Rev	ision	history	16		



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DS2063 - Rev 5 page 18/18